- 3-03; 2:14PM; ;19496600809 # 3/ 7

Atty Docket No.: JCLA7737

Serial No.: 10/015,414

IN THE CLAIMS:

Please amend the claims as follows.

5. (Currently Amended) A method of erasing a non-volatile memory <u>cell</u> with a nitride tunneling layer, the non-volatile memory having a substrate, a nitride tunneling layer on the substrate, a charge-trapping layer on the nitride tunneling layer, a dielectric layer on the charge rapping layer, a gate conductive layer on the dielectric layer, and a source region and a drain region in the substrate beside the gate conductive layer, and the method comprising the steps of:

a substrate;

a nitride tunneling layer disposed on the substrate;

a charge-trapping layer disposed on the nitride tunneling layer;

a dielectric layer disposed on the charge-rapping layer;

a gate conductive layer disposed on the dielectric layer; and

a source region and a drain region disposed in the substrate beside the gate conductive

layer;

the method comprising the steps of:

applying a first positive bias to the drain region, applying a second positive bias to the gate conductive layer, and grounding the source region and the substrate to generate hot electron holeselectron/holes in a channel region, wherein the hot electron holeselectron/holes are injected into the charge-trapping layer through the nitride tunneling layer.

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- 6. (Original) The method of claim 5, wherein the first positive bias ranges from about 2V to about 5V.
- 7. (Original) The method of claim 5, wherein the second positive bias ranges from about 2.5V to about 5V.
- 8. (Original) The method of claim 5, wherein the first positive bias and the second positive bias are both lower than those adopted for erasing a substrate-oxide-nitride-oxide-silicon (SONOS) memory having a same size as the non-volatile memory with the nitride tunneling layer.